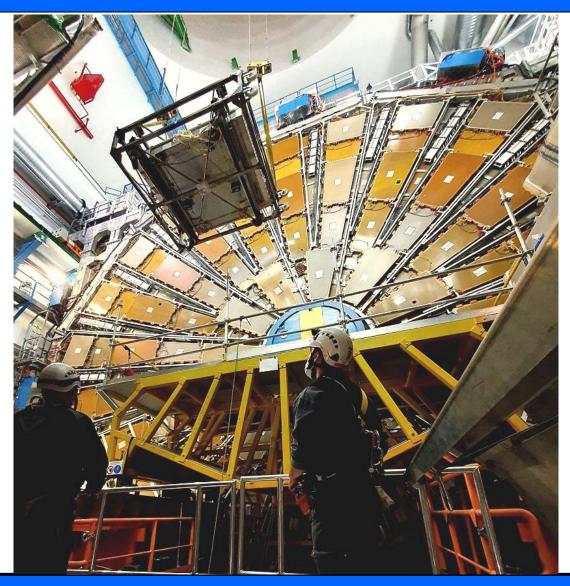
ATLAS Muon Spectrometer Upgrades



On behalf of the MDT and Minerva groups

Hubert Kroha

Ringberg 17.01.2023

ATLAS Muon Upgrades



- Phase- 0 and 1 Muon System upgrades in LS1 (BME), EYETS (BMG) and LS2 (BIS78), proposed and developed by MPP, completed. Chambers installed and in operation. Initiative, R&D and design for New Small Wheels upgrade.
- Phase-2 Muon System upgrades in LS3, proposed, developed and coord. up to TDR by MPP:
 96 new BIS sMDT detectors (design MPP, construction MPP & Michigan 50:50).

Coordination MPP.

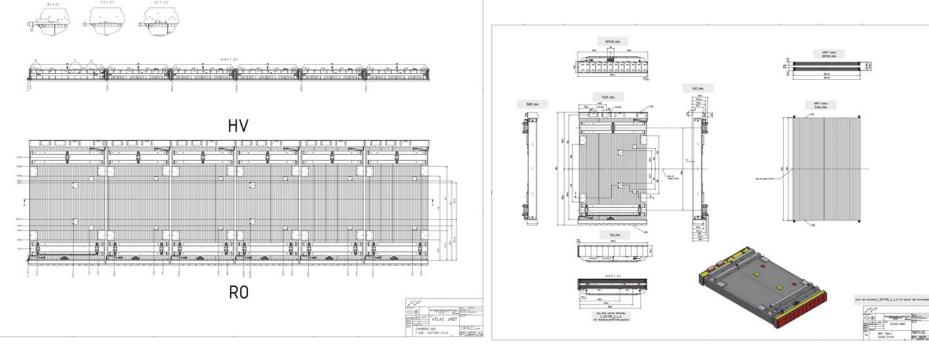
- 275 new BIS and BIL RPC chambers (gas gap design and construction MPP & INFN 50:50). BIS coordination MPP.
- First-level hardware muon track trigger based on (s)MDT precision tracking chambers (trigger processor hard- and firmware design MPP, production MPP & Boston & Japan). Co-coordination MPP.
- New (s)MDT chamber front-end boards (design MPP, production and test LMU & Würzburg). Coordination MPP, 16.000 pcs. (3.000 pcs.)
- New ASD ASICs (design MPP, production MPP & LMU, 80.000 pcs.) Coordination MPP.
- New TDC ASICs (design and production MPP & Michigan 50:50, 20.000 pcs.)

BIS Layer Design: sMDT

Layout of new BIS layer:

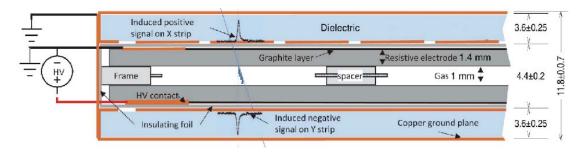
Design of sMDT chambers:

10 different types with different services and alignment connections

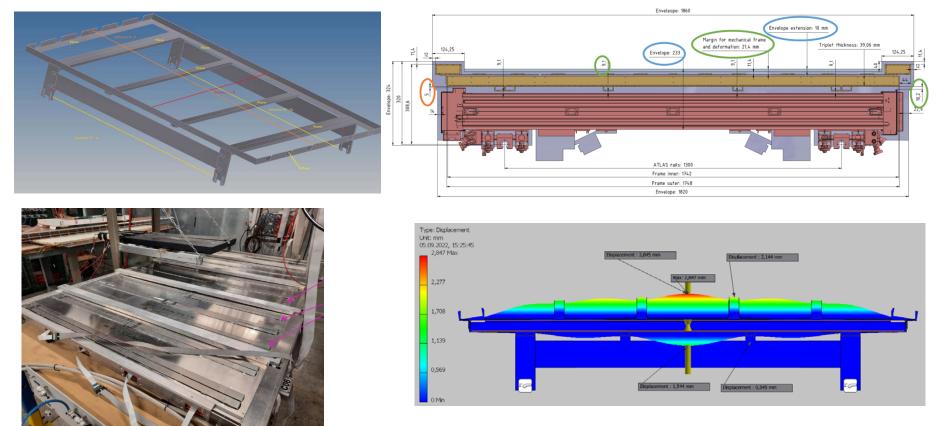


BIS Layer Design: RPC

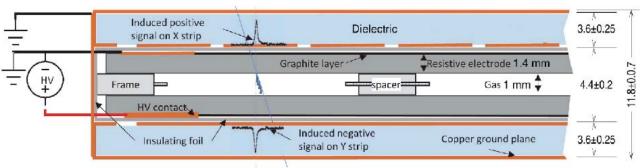
Design of RPC gas gaps:



Design of support frames for RPC triplets. Integration of sMDT and RPC chambers:



Thin-Gap RPC Trigger Chamber Design and Production



Thin-gap RPC design completed:

10 x improved lifetime and rate capability, sub-ns time resolution

Reliable and sustainable industrialized mass production is required for ATLAS (and many other applications).

RPC construction procedures established at MPP in 2021/22.

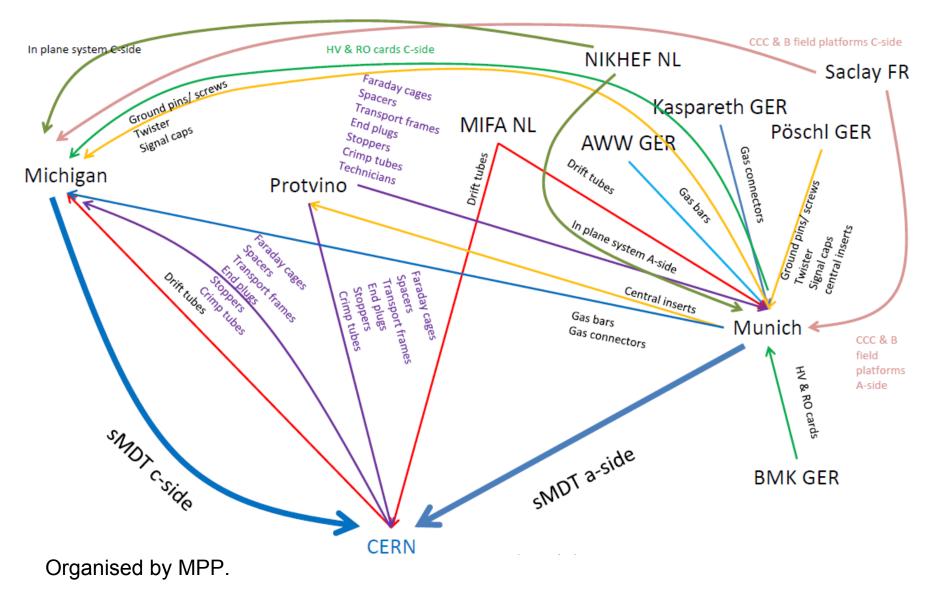
Successful Technology transfer to two german companies for the mass production for the ATLAS upgrade in 2022–2024.

Gas gap prototype construction and qualification under irradiation at GIF in 2023.

Gas gap production in 2024 -25.



sMDT Production Logistics

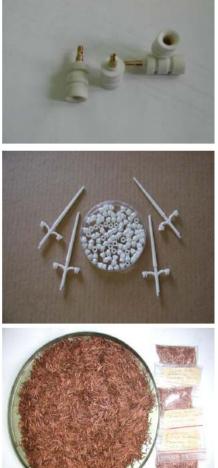


Early procurement essential for timely completion of sMDTs ahead of ATLAS schedule.

IHEP Protvino sMDT In-kind Contributions

Injection molded drift tube endplugs

Chamber rail supports



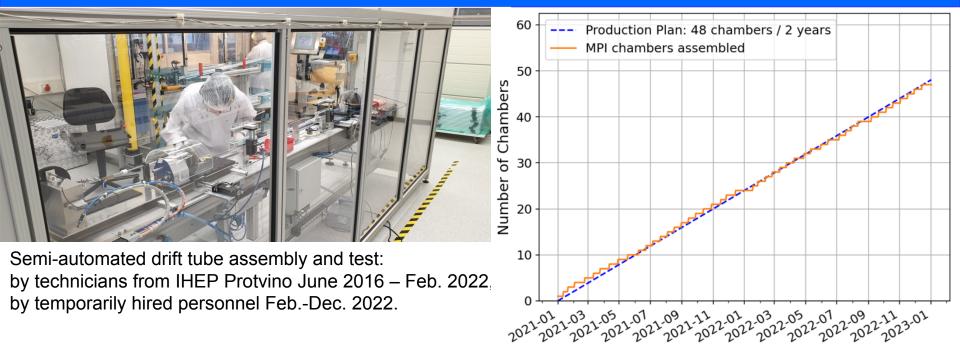


sMDT transport and storage frames





sMDT Chamber Production



Serial production of 48 BIS 1-6 sMDT chambers at MPP Jan. 2021 – Jan. 2023 at a steady rate of 2 chambers per month as planned.

The other 48 chambers produced at University of Michigan March 2021 – Oct. 2023. Successful technology transfer in 2020-2021.

The only Phase-2 upgrade project in production and on (ahead of) schedule in ATLAS (together with the MDT front-end electronics designed by MPP).

sMDT Chamber Production





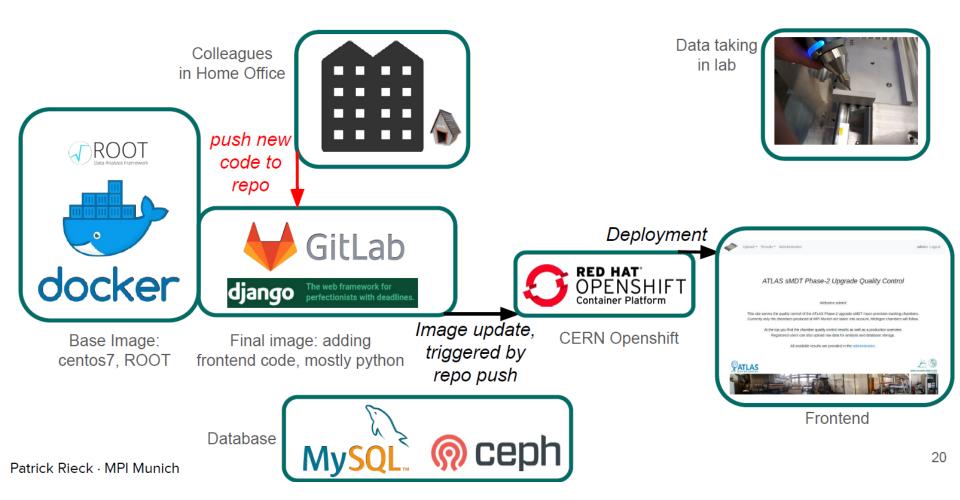


sMDT Chamber Production



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Chamber Production Quality Monitoring



Chamber Precision and Performance

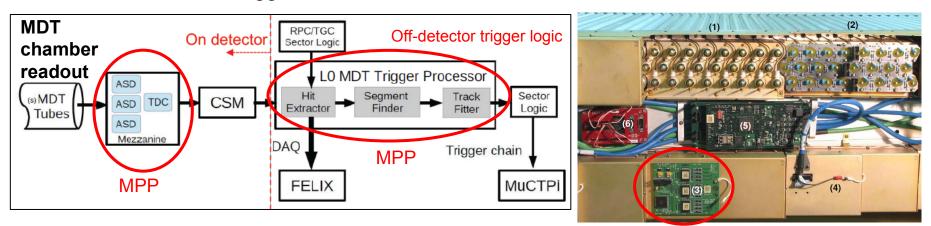
Sense wire position measurement with Wire positioning accuracy: automated coordinate measuring machine: 5 µm wire pos. accuracy achieved in serial production (requirement 20 µm) Wire locator (brass spiral) Plastic insulato Ē Residual width r [micron] 6.5 60 1 µm 5.5 5.0 4.5 4.0 BIS3 A04, HV BIS5 A04, HV A06, HV H Η BIS1 A08, HV BIS1 A10, HV 3IS1 C12, HV 3IS1 A14, HV BIS1 C16, HV BIS2 A02, HV BIS3 A02, HV BIS5 A02, HV BIS6 A02, HV BIS2 A04, HV BIS6 A04, HV Η Η Η Η ₹ Η ₹ BIS2 A06, H BIS3 A06, H BIS4 A04, I A02, I BIS1 A02, 3IS1 A04, BIS5 A06, BIS6 A06, A06, 140 sMDT Resolution [µ m] ATLAS Internal BIS1 BIS4 BIS4 130 Observed Average Observed 120 96.0±4.5µ m Spatial DT resolution of serial prod. chambers 110 with legacy electronics 100 with new ASD for Phase 2 90 80 70 2 3 5 10 11 4 6 8 9 12 **BIS Module Number**

Chamber Storage and Test at CERN BB5 Hall

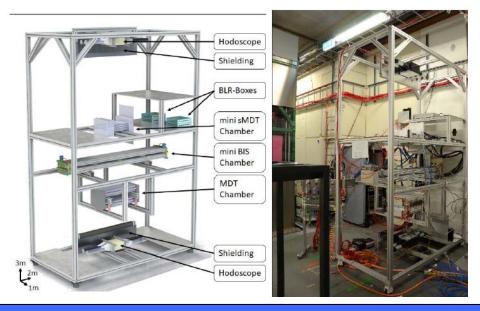


New (s)MDT Readout Electronics

To cope with 10 x higher 1st level trigger rates and latency and continuous MDT readout for the new MDT track trigger.

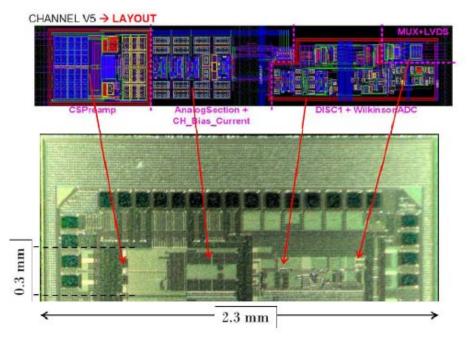


Full on-detector readout chain validated in the CERN GIF in Nov. 2021 with pre-production chips:

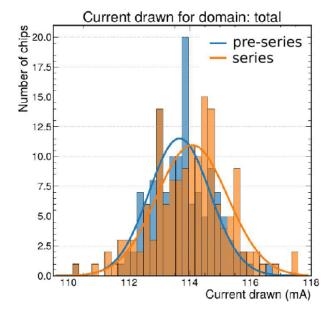


MDT ASD ASIC Development

ASD ASIC in Global Foundry 130 nm CMOS technology:



Pre-series production in 2019. Delivery of packaged series chips in January 2021. Excellent performance , 92% yield.



Arrival of 80k chips at MPP:

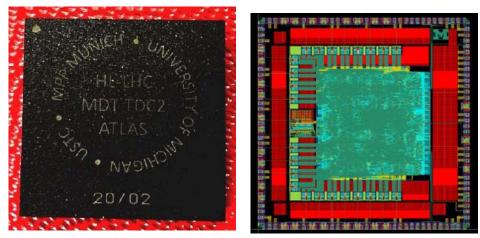


Further development in progress:

Updated version in sustainable TSMC 65 nm CMOS technology

- with reduced power consumption
- still faster shaping for pile-up reduction
- active baseline restoration functionality

TDC ASIC and MDT Front-end Boards



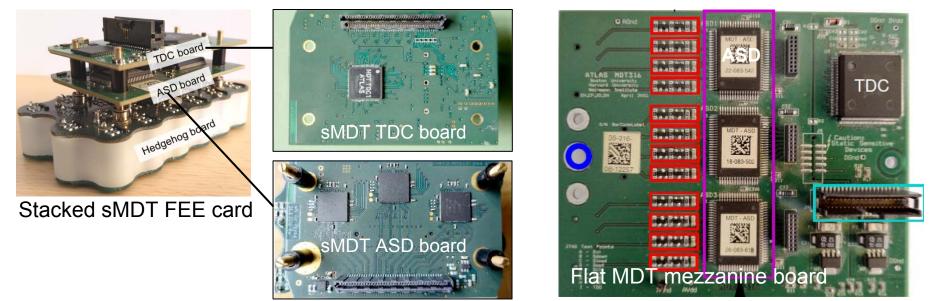
TDC ASIC in TSMC 130 nm CMOS technology.

Pre-production in 2021.

Serial production of 20k chips in 2022.

Design of (s)MDT front-end (mezzanine) cards ready (freelancing engineers from Yerevan).

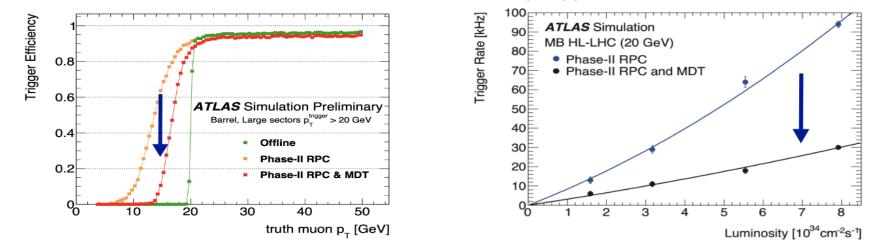
Production start in fall 2023 after delivery of rad. hard low-voltage regulators (LDOs); neutron and proton irradiation test campaign and selection in 2021.



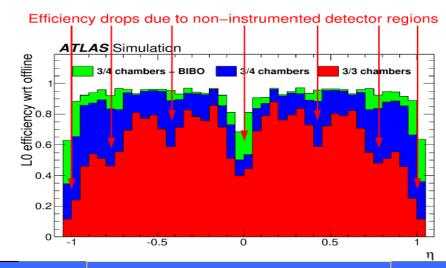
New MDT Based Muon Track Trigger

MPP concept:

Improvement of momentum resolution and selectivity of the 1st level muon trigger by almost an order of magnitude by making use of the high spatial resolution of the (s)MDT chambers with continuous readout in order to suppress the overwhelming trigger rate from low-momentum muons.



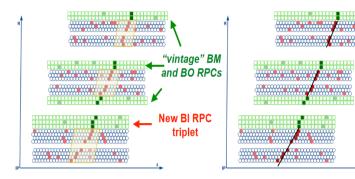
In addition, closing of trigger acceptance gaps in the barrel and backup for legacy RPCs & TGCs:



MDT Trigger Algorithm

Implemented on FPGAs, performs pattern recognition, track fitting and transverse momentum determination within 1 µs. Compact solution developed by MPP. Coordinated by MPP.

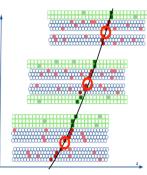
Hit extraction: match MDT hits with candidates from SL, provide calibrated hit positions



Muon candidate pipeline ~ 1us

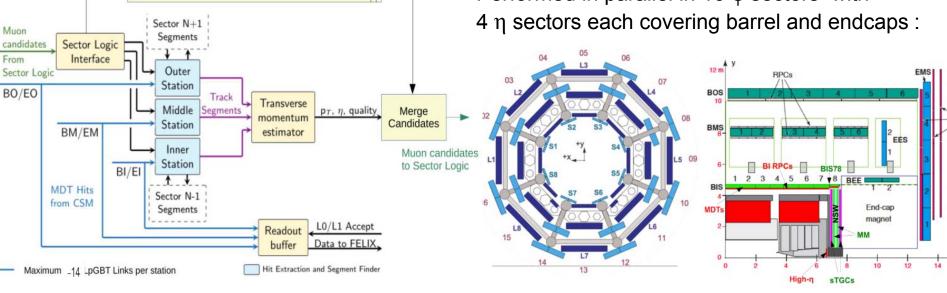
Segment finding: fit straight track segments in each station

pr estimation: derive momentum estimate from group of segments



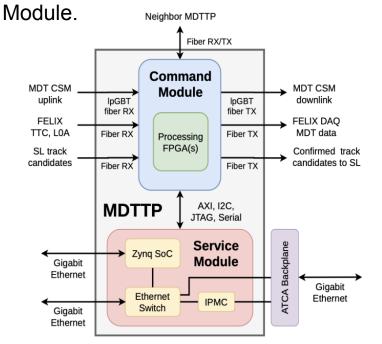
Seeds and BCID from RPC/TGC hits via the Sector Logic (SL).

Performed in parallel in 16 ϕ sectors with



MDT Trigger Processor Hardware

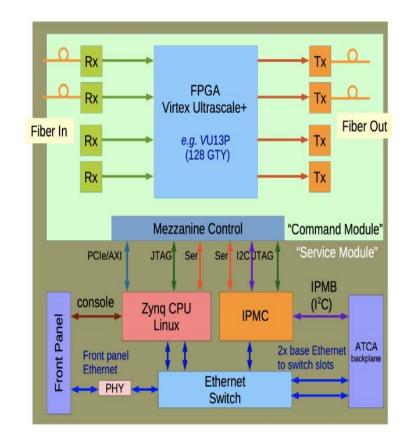
64 ATCA trigger processor blades, consisting of a Service Module carrying the Command



Service module



The Command Module carries the FPGA and a large number of 10 Gbps optical transceivers (MPP design, in cooperation with company)



Command Module Status

First demonstrator modules produced and tested in 2020-21. Proof of trigger algorithm implementation and latency on FPGA.



Final prototype designed and produced 2021-22. Validation in 2023.

Production and test in 2024-2025.

Needed for the commissioning of the new muon chambers and electronics in ATLAS.



Schedule Overview

MPP responsibilities	Т	20	21			2	022			202	23			20	24			20	25			20	26			202	7			20	028		
	Q1	Q2	Q3	Q4	Q1	Q,2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q 2	Q3	Q4	Q1	0,2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	
BIS1-6 A sMDT construction at MPP	Т																																
BIS sMDT frontend board production																																	sMDT
BIS1-6 A, BIS78 C sMDT comm.w. final elx.at CERN																																	
BIS1-6 RPC design																																	
BIS1-6 gas gap production, test at CERN																																	
BOS RPC design																																	
BOS RPC gas gap production																																	RPC
BIS1-6 RPC frame production																																	
BIS1-6 RPC triplet integration at MPP																																	
BIS1-6 A, BIS78 C sMDT+RPC triplet integration at CERN	Г																																
MDT frontend board production and test	Г																																
MDT trigger processor production and test																																	Elx.
BIS1-6 A, BIS78 sMDT+RPC installation/commissioning																																	Triagor
MDT trigger module installation/commissioning																																	Trigger
MDT frontend electronics installation/commissioning																																	

Start LS3

21

13.12.2021 Hubert Kroha	
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